AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph at page 2, lines 5–11 of the specification with the following:

The present invention relates generally to packaging integrated circuit devices and in particular to providing electrical discharge properties to integrated circuit device packaging. Still more particularly, the present invention relates to forming a metal ring around an integrated circuit from a portion of a lead frame for the purpose of conducting electrostatic energy away from the integrated circuit.

Please replace the paragraph bridging page 8, line 26 through page 9, line 9 of the specification with the following:

As illustrated in **Figure 1E**, the electrostatic discharge ring formed by the folded portions of lead frame **108b** and **108c** may extend along a ~~peripheral edge~~ side ~~**118a**~~ of packaged integrated circuit **102** from which ~~is opposite~~ pins **116** project, with an opening **118d** through the folded lead frame portions **108b** and **108c** allowing access to pins **116** for an external connector as depicted on the right side of **Figure 1E**. Alternatively, the electrostatic discharge ring may contain a broken region **118e** along a ~~peripheral edge **118b** opposite~~ side from which pins **116** project. The

required length of the pins which must remain exposed for a connector, the thickness of the integrated circuit **104** and plastic or epoxy material **112**, and other design considerations may affect whether the electrostatic discharge ring extends along a complete circumference of the packaged integrated circuit **102**.

Please replace the paragraph at page 12, lines 1–13 of the specification with the following:

During lead frame trim and form operations, sections of each lead frames will be folded along the dashed fold lines **312** and trimmed along dashed trim lines **314** depicted in **Figure 3B**. These sections will be folded up around the sides and over a peripheral upper surface of the integrated circuit package to form the electrostatic discharge ring. These sections remain physically and electrically connected to the lead frame die paddle on which the integrated circuit die is mounted, and are connected through the lead frame to a grounding connection. When a human finger touches the electrostatic discharge ring formed from these folded sections in contacting the sensing surface of the packaged integrated circuit, any electrostatic charge is dissipated to ground by the electrostatic discharge ring.